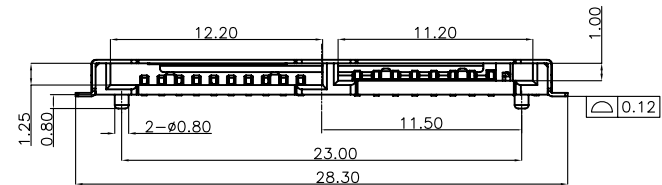
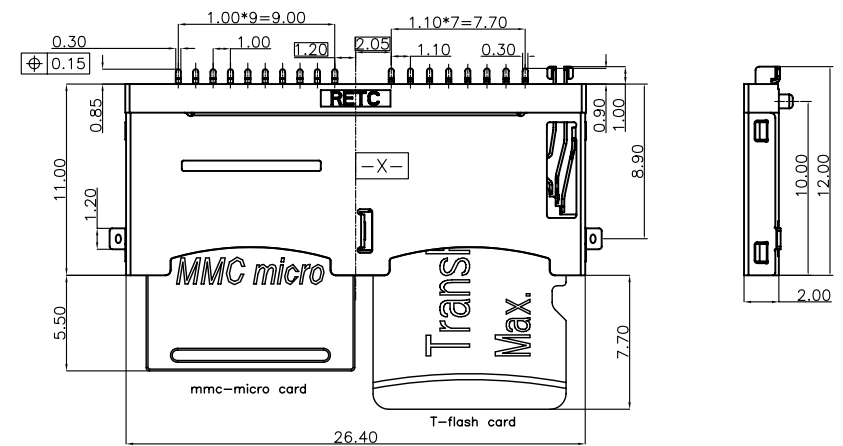


RECOMMENDED PCB LAYOUT
(GENERAL TOLERANCE ±0.05)



SPECIFICATION

1.MATERIAL

Insulator: High Temperature Thermoplastic, UL94V-0
Contact: Copper Alloy
Shell: Copper Alloy

2.PLATING

Contact Area: Gold PLATED Over Ni.
Solder Tail: Sn PLATED Over Ni.
Shell Solder Area: Gold PLATED Over Ni.

3.ELECTRICAL

Operating Temperature:-25°C TO+90°C
Current Rating :0.5mA max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500VDC

4.MECHANICAL

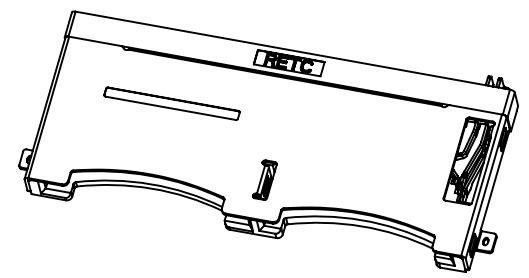
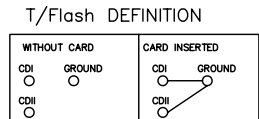
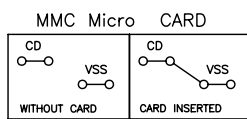
Mating Cycles:10,000 Insertions

MMC MICRO

| PIN No. | PIN DEFINITION |
|---------|----------------|
| 1# | DAT 2 |
| 2# | DAT 3 |
| 3# | CMD |
| 4# | CD |
| 5# | VDD 1 |
| 6# | VDD 2 |
| 7# | CLK |
| 8# | VSS |
| 9# | DAT 0 |
| 10# | DAT 1 |

T/Flash DEFINITION

| PIN NO. | FUNCTION |
|---------|------------------------------|
| 1 | DATA LINE(BIT 2) |
| 2 | CARD DETECT/DATA LINE(BIT 3) |
| 3 | COMMAND RESPONSE |
| 4 | SUPPLY VOLTAGE |
| 5 | CLOCK |
| 6 | SUPPLY VOLTAGE GROUND |
| 7 | DATA LINE(BIT 0) |
| 8 | DATA LINE(BIT 1) |



| | | | | | | | | |
|--|------------|--|-----------------------|---------------------------|----------------|----------------------------------|------------|--------|
| UNLESS OTHERWISE SPECIFIED TOLERANCE TO BE | | DRN: NEIL | DATE: 2008.05.05 | A | 新发行 | NEIL | 2008.05.05 | |
| LINEAR | ANGULAR | CKD: DAVID | DATE: 2008.05.05 | REV. | CHANGE DETAILS | BY | DATE | CHG/No |
| .X ± 0.38 | .X ± 2° | APP'D: KING | DATE: 2008.05.05 | TITLE: MICRO SD+MMC MICRO | | RETC 深圳市锐泰科电子有限公司 | | |
| .XX ± 0.25 | .X ± 1° | DO NOT SCALE | SCALE: 4:1 | 3IN1 双槽板上 | | TEL:86-755-27882199 FAX:27882798 | | |
| .XXX ± 0.10 | .XX ± 0.5° | BREAK ALL SHARP EDGES AND REMOVE ALL BURRS | | THIRD ANGLE PROJECTION | | DRAWING NO. | | SHEET |
| DIMENSIONS IN MILLIMETRES | | | PART NO.: 100-203-121 | SIZE: A4 | 100-203-121-1 | | 1/1 | |